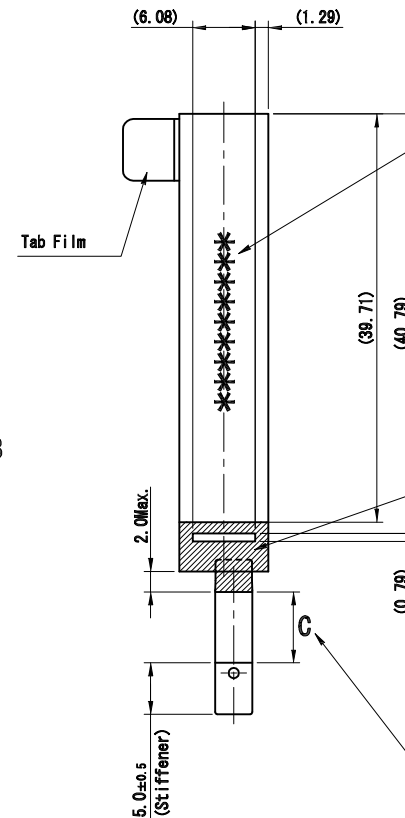
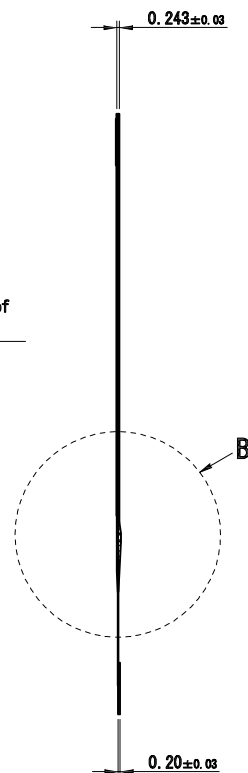


Resin on Display Side  
 1) Wiring patterns on FPC must be covered with resin entirely.  
 2) The thickness must be lower than the thickness of film.  
 Applied Permissible Area  
 Up to 2.0 length from the edge of film on FPC.

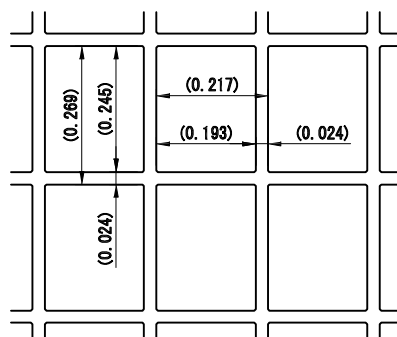
Contact side of connector



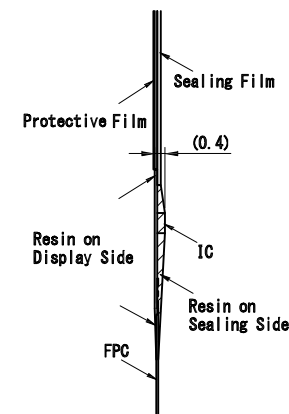
Printed Location of Manufacturing No.  
 1) It must be printed within sealing film.  
 2) Reversing printing is acceptable.

Resin on Sealing Side  
 1) Wiring patterns on glass panel must be covered with resin entirely.  
 2) The thickness must be lower than the height of IC.  
 Applied Permissible Area  
 1) Up to edges of film (no sides).  
 2) Up to sides of sealing film.  
 3) Up to 2.0 length from the edge of film on FPC.

C Limit ... Applied Permissible Area of FPC Bending Location  
 1) 2.0 length or more over from the edge of film.  
 2) Up to the edge of stiffener.  
 Applied Permissible Bending Radius  
 It must be 0.38 or more over.



A-Portion Magnified Drawing(100:1) B



B-Portion Magnified Drawing(5:1)